Central™
Semiconductor Corp.
145 Adams Avenue, Hauppauge, NY 11788 USA
Tel: (631) 435-1110 • Fax: (631) 435-1824
www.centralsemi.com
mailto:processchange@centralsemi.com
http://www.centralsemi.com/processchange

PCN #152

**Notification Date:
2 February 2015**

Product / Process Change Notice

Parts Affected:
Chip process CP707, NPN silicon small signal transistors, wafers, and bare die.

Extent of Change:
The CP707 wafer process has been discontinued and replaced with the CP727V wafer process.
The overall wafer diameter was increased from 4 inch to 5 inch.
The overall wafer thickness was reduced from 9 mils to 7.1 mils.
The backside metallization (Au) was reduced from 18,000Å to 9,000Å.
The die size was reduced from 27 x 27 mils to 22.8 x 22.8 mils.
The die pattern and bond pad area were changed; see figures 1 and 2 for details.

Reason for Change:
Process transfer from the 4” wafer fab to the 5” wafer fab.

Effect of Change:
This change does not affect the electrical characteristics of any device.

Qualification:
Standard evaluation and qualifications completed resulting in no performance differences compared to current product.

Effective Date of Change:
May 1, 2015. Existing inventory will be shipped until depleted.

Sample Availability:
Please contact Salesperson or Manufacturer’s Representative.

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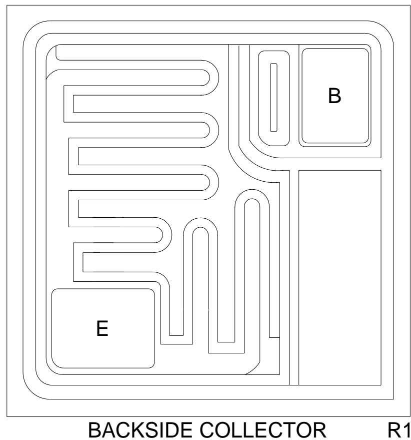
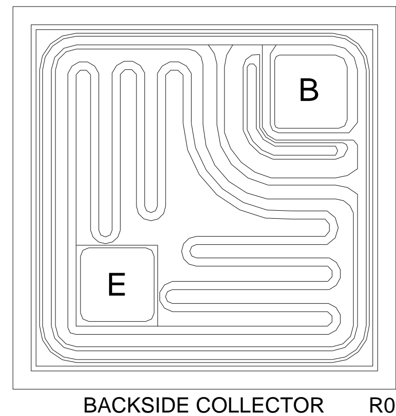
Figures:

Figure 1: CP707 Chip Geometry (Discontinued)



Wafer Diameter:	4 inch
Die Size:	27 x 27 mils
Die Thickness:	9.0 mils
Bond Pad Size (Emitter):	5.3 x 6.5 mils
Bond Pad Size (Base):	5.3 x 3.8 mils
Topside Metal:	Al (30,000Å)
Backside Metal:	Au (18,000Å)

Figure 2: CP727V Chip Geometry



Wafer Diameter:	5 inch
Die Size:	22.8 x 22.8 mils
Die Thickness:	7.1 mils
Bond Pad Size (Emitter):	4.7 x 4.7 mils
Bond Pad Size (Base):	4.7 x 4.7 mils
Topside Metal:	Al (30,000Å)
Backside Metal:	Au (9,000Å)

Part Numbers Affected:

MPSA62
MPSA63
MPSA64
MPSA65
MPSA66
MPSA75
MPSA76
MPSA77
CXTA62
CXTA64
CZTA64
CZTA77
CEN-U95
CMPTA63
CMPTA64
CMPTA77
CP707-MPSA64-WN
CP707-MPSU95-WN
CP707-CMPTA64-CTO
CP707-MPSU95-CT